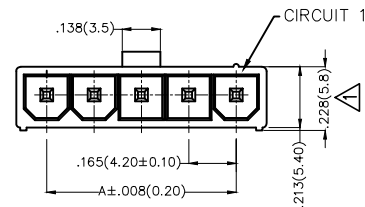
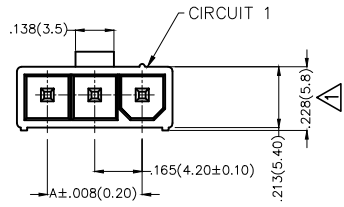
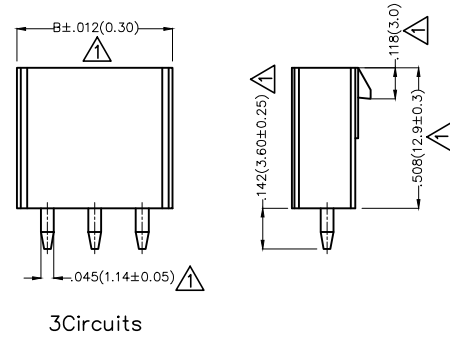


REV	LOCATIONS	DESCRIPTION	DATE	REVISED	APPD
1	△	Size change	07/FEB/21	KATE	CHERRY

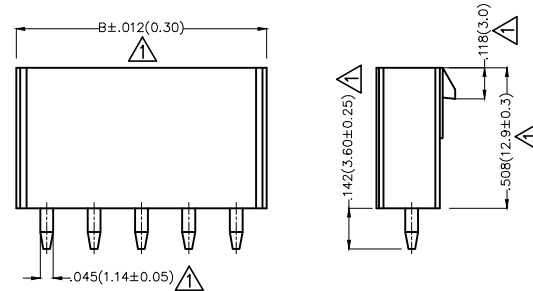


Electrical  
 Current Rating: 9A AC(rms)/DC  
 Voltage Rating: 600V AC(rms)/DC  
 Contact Resistance: 10 mΩ Max  
 Insulation Resistance: 1000 MΩ MIN  
 Withstanding Voltage: 1500V AC r.m.s  
 Temperature Range—Operating: -40°C ~ +105°C

Material and Plating  
 Housing: PA66( UL 94V-2)  
 Contact Pin: Brass  
 Plating: Tin Plated



3Circuits



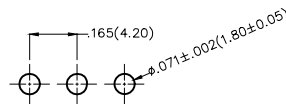
2,4,5,6Circuits

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF42006-S02S22TB	.165(4.20)	.379(9.60)
3	FWF42006-S03S22TB	.331(8.40)	.543(13.80)
4	FWF42006-S04S22TB	.496(12.60)	.709(18.00)
5	FWF42006-S05S22TB	.661(16.80)	.874(22.20)
6	FWF42006-S06S22TB	.827(21.00)	1.039(26.40)


Ordering Information

FWF 420 06 - S XX S 2 2 T B  
 1 2 3 4 5 6 7 8 9 10

1   Category FWF-Wafer	2   Series Number 420-Pitch4.2mm	3   Distinction No. 06	4   Row Option Single Row	5   Circuits XX	6   Entry Angle S-180° Vertical
7   Plating 2-Tin Plated	8   Material-Resin 2-PA66	9   Color-Resin T-Transparent	10   Packaging B-PE Bag		



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF42006-SXXS22TB	ITEM NO. FWF42006	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20)	X.±5° .X'±2'	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 4.2mm 180° Vertical (DIP)		REV 1
SCALE 5:1	SIZE A4	X.XX±.006(0.15) X.XXX±.004(0.10)	.XX'±1° .XXX'±0.5°	DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		